

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-029406

(43)Date of publication of application : 05.02.1993

(51)Int.Cl.

H01L 21/66  
G01R 1/073  
G01R 31/26

(21)Application number : 03-178179

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(22)Date of filing : 18.07.1991

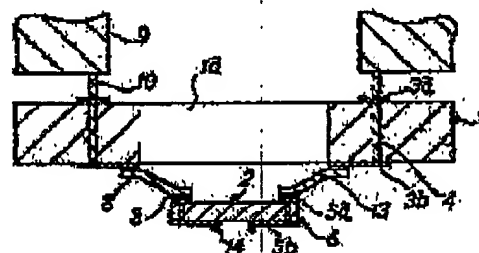
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## (54) SEMICONDUCTOR INSPECTION APPARATUS

## (57)Abstract:

**PURPOSE:** To obtain a semiconductor inspection apparatus wherein, irrespective of the parallelism of the surface of a semiconductor wafer to the surface of an inspection board, the good electric contact of an electrode pad on the semiconductor wafer with a bump electrode on the inspection board is ensured and the reliability of an inspection is increased.

**CONSTITUTION:** A plurality of wiring patterns 3a, 3b which have been connected electrically by a through hole 4 are formed on both faces of a probe card 1. A plurality of wiring patterns 5a, 5b which have been connected electrically by a through hole 6 are formed on both faces of an inspection board 2. The inspection board 2 is supported elastically by the probe card 1 in a state that the wiring pattern 5a has been connected electrically to the wiring pattern 3b by means of a tungsten wire 13. A bump electrode 14 which is provided with a sharp tip shape is formed at the end part of the wiring pattern 5b on the inspection board 2.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of

OCT. 6. 2005 3:38PM

KIRTON & MCCONKIE

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rejection]

[Kind of final disposal of application other than  
the examiner's decision of rejection or  
application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's  
decision of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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